CORRECTION

Correction to: Fracture of Sn-3.5%Ag Solder Alloy Under Creep

V.I. IGOSHEV,¹ J.I. KLEIMAN,¹ D. SHANGGUAN,² S. WONG,³
 and U. MICHON⁴

1.—Integrity Testing Laboratory Inc., 80 Esna Park Drive, Units 7-9, Markham, ON L3R 2R7, Canada. 2.—Visteon Automotive Systems, Deaborn, MI 48121, USA. 3.—Visteon Automotive Systems, Markham, ON, Canada. 4.—ESPEO.3, Universite D'Orleans, Orléans, France.

Correction to:
Journal of ELECTRONIC MATERIALS,
Vol. 29, No. 12, 2000
<https://doi.org/10.1007/s11664-000-0119-z>

In the original article, there is an error in Fig. 8.
 Following is the corrected figure.

Fig. 8. Dependence of specimen (Sn-3.5%Ag solder alloy) lifetime τ_c , vs. the applied creep stress σ at different temperatures.